

Immersion Gold SLOGOLD 10

Immersion Gold SLOGOLD 10 has been developed in order to deposit 24 carat gold layers by simple electroless dipping.

The electrolyte is especially suitable for gold plating of nickel, copper and copper alloys. Gold deposition is due to metal exchange in which relatively even gold coatings with a thickness of up to max. 0.1 µm and excellent bonding capability can be achieved. The degree of brightness is equivalent to the brightness of the base material.

Immersion Gold SLOGOLD 10 is applied if electroplating gold processes fail due to their restricted covering power.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read these instructions carefully and follow recommendations given. We reserve the right to make technical changes as necessary. In the interests of safety, please pay attention to the R- and S- phrases on the labels of the containers. The minimum shelf life of the additives is printed on the label of the container. The current IMDS number of the layer deposited from the process can be found on the internet at www.schloetter.com/downloads.

For the storage of chemical products only the TRGS 514 and TRGS 515 regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) is only valid **for transportation** and must not be applied to storage.

